

In the claims:

Cancel claim 8 without prejudice.

Add the following claim:

14. A laser diode arrangement, comprising a joint electrically insulating substrate, a plurality of laser diodes mounted on said joint electrically insulating substrate; conductor structure provided on said electrically insulating substrate and connecting said laser diodes with one another in series; means for joint control of said laser diodes; and short circuit bridges which provide low-ohmic bridging of poor or defective laser diodes.

Amend the following claims:

B1  
1. A laser diode arrangement, comprising a joint electrically insulating substrate[,] having high thermal coefficient; a plurality of laser diodes [arranged in] mounted on said joint electrically insulating substrate; conductor structure provided on said electrically insulating substrate and connecting said laser diodes with one another in series; and means for joint control of said laser diodes.

B2  
7. A laser diode arrangement as defined in claim [1] 6; and further comprising a support on which said substrate is located; and further conductor structures applied on said support and contacting with said first-mentioned conductor structures on said substrate through second bond wires.

Amended claims:

1. A laser diode arrangement, comprising a joint electrically insulating substrate having high thermal coefficient; a plurality of laser diodes mounted on said joint electrically insulating substrate; conductor structure provided on said electrically insulating substrate and connecting said laser diodes with one another in series; and means for joint control of said laser diodes..

7. A laser diode arrangement as defined in claim 6; and further comprising a support on which said substrate is located; and further conductor structures applied on said support and contacting with said first-mentioned conductor structures on said substrate through second bond wires.